

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Patent Application:  
Rajeev Joshi et al.

Serial No.: 10/618,113

Filed: July 11, 2003

For: WAFER-LEVEL CHIP SCALE PACKAGE AND  
METHOD FOR FABRICATING AND USING THE  
SAME

Confirmation No. 8697

Group Art Unit: 2829

Examiner: Zarnecke, David A.

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Mail Stop Non-Final Response  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

**REQUEST FOR RECONSIDERATION UNDER 37 C.F.R. § 1.111**

In response to the Office Action mailed June 20, 2006, Applicant requests reconsideration of this application in light of the following remarks.

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to:  
Commissioner for Patents, Alexandria, VA 22313-1450, on this 12th day of September 2006.

Signed: \_\_\_\_\_

9/12/2006